

In the Specification:

Please replace the paragraph beginning on page 3, lines 11-28, with the following new paragraph:

One or both of the connectors may be formed by cutting through the patch 3. As shown in Figure 2, for example, the feed connector 33 is formed by cutting through the patch 3 and leaving an internal cutout 31. For the purposes of the present invention, the terms “cut” or “cutting” include any means of forming a connector from within the periphery of patch 3 whether by stamping, cutting, etching, engraving, scoring, and the like ~~{any other examples here?}~~. Alternatively, a connector may be formed by cutting through the patch 3, such that the cutout 31 extends to the periphery of the patch 3. The cutout 31, whether internal or extending to the periphery of the patch 3, influences the radiating of the PIFA 4 in the same manner as the cutout 32. Although the cutout 31 is shown as a straight line, the cutout may alternatively form any other shape desired to improve the RF performance of the PIFA 4. For example, the cutout 31 may alternatively include a circle, an arc, a zip-zag line, a meanderline, or any other geometric or irregular shape as desired to alter the RF performance of the PIFA 4. Further, although the feed connector 34 shown in Figures 2 and 4 is shown substantially coextensive with the cutout 31, the feed connector 34 (or the ground connector 33) may also be a portion of a larger cutout area.

Please replace the paragraph beginning on page 4, lines 3-8, with the following new paragraph:

The carrier 2 may be formed of any suitable non-conducting material such as a dielectric ~~{or insulator?}~~ or insulator material (e.g., plastic molding). The carrier 2 supports the patch 3 and maintains the patch 3 in the location relative to the PCB of a wireless communication device. The carrier may be attached to the PCB by any means known in the art, such as by clipping, fixing with screws, and the like.